What is claimed is:

1. A chip type light emitting device comprising:

a board of nearly rectangular shape in a plane view;

first and second electrode patterns formed at both ends of a surface of said board;

a light emitting diode (LED) chip mounted on said first electrode pattern;

a metal wire connected to said LED chip and said second electrode pattern by wire bonding; and

a translucent resin mold which seals said LED chip and said metal wire;

wherein one notch is formed at one end of said board at said first electrode pattern side and two notches are formed at both sides of the other end of said board at said second electrode pattern side, and the positions at both ends of said translucent resin mold are arranged to the positions at both ends in a longitudinal direction of said board.

2. The chip type light emitting device of claim 1, wherein said LED chip is almost centered on said board.

3. The chip type light emitting device of claim 1, wherein said board size is 1.6 mm x 0.8 mm or less.

4. The chip type light emitting device of claim 1, wherein said metal wire is connected to said LED chip and the surface of said second electrode pattern, which is located between said two notches formed at both sides of the other end of said board at said second electrode pattern side, by wire bonding.

5. The chip type light emitting device of claim 1, wherein said one notch formed at said one end of said board at said first electrode pattern side is semi-cylindrical and said two notches formed at both sides of the other end of said board at said second electrode pattern side are quarter-cylindrical.